

SOT409B1

ceramic surface mounted package; 8 leads

8 February 2016

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	CDIP8
Package type industry code	CDIP8
Package style descriptive code	CDIP (ceramic dual in-line package)
Package style suffix code	NA (not applicable)
Package body material type	C (ceramic)
Mounting method type	S (surface mount)
Issue date	27-1-1998

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	5.03	-	5.48	5.94	mm
E	package width	4.01	-	4.47	4.93	mm
A	seated height	2.06	-	2.21	2.36	mm
e	nominal pitch	-	-	1.27	-	mm
n ₂	actual quantity of termination	-	-	8	-	



2. Package outline

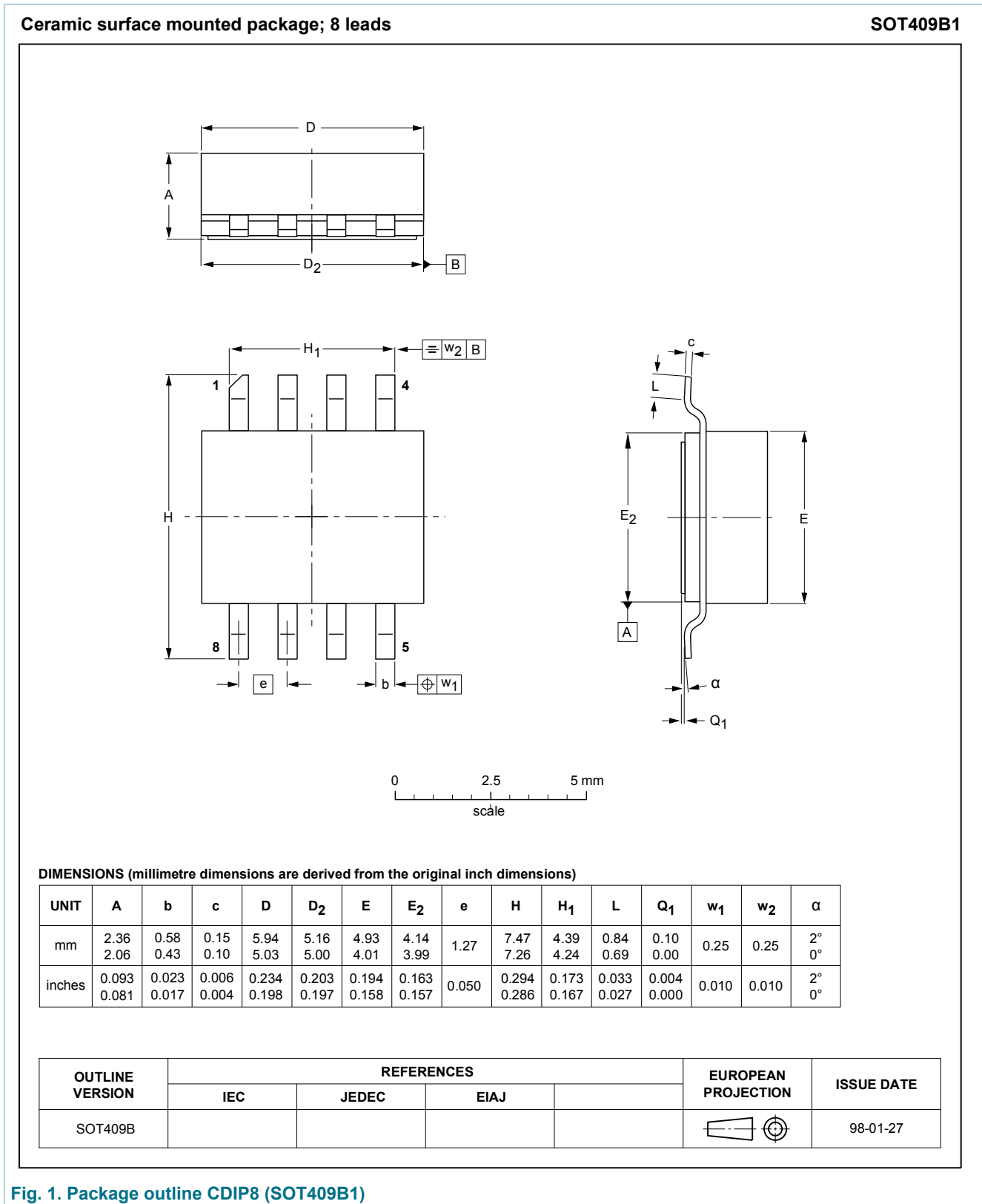


Fig. 1. Package outline CDIP8 (SOT409B1)

3. Legal information

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